


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 22 October 2012 [Approved on 14 June 2016, 10:36 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3.89000%	Silver	7440-22-4	19.44000%
			Silicon	7440-21-3	80.56000%
Die attach	Sn-Pb solder	4.37000%	Silver	7440-22-4	2.73000%
			Tin	7440-31-5	4.92000%
			Lead	7439-92-1	92.35000%
Encapsulation	EP (Epoxy resin)	44.78000%	Carbon black	1333-86-4	0.50000%
			ALUMINUM(III) HYDROXIDE	21645-51-2	2.80000%
			resin	9003-35-4	8.60000%
			Epoxy resin 89	26335-32-0	18.00000%
Leadfinish	Tin plating	0.55000%	Crystalline silica	14808-60-7	70.10000%
			Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	46.41000%	iron	14127-53-8	0.15000%
			Copper	7440-50-8	99.85000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
TO-277 B	Power SMD	0.1	g